(12) INTERNATIONAL APPLICATION PUBLISHED UNDER THE PATENT COOPERATION TREATY (PCT)

(19) World Intellectual Property Organization
International Bureau

(43) International Publication Date
4 January 2001 (04.01.2001)

PCT

(10) International Publication Number
WO 01/01480 A1

(51) International Patent Classification[7]: H01L 21/768

(21) International Application Number: PCT/US00/40108

(22) International Filing Date: 5 June 2000 (05.06.2000)

(25) Filing Language: English

(26) Publication Language: English

(30) Priority Data:
09/345,586 30 June 1999 (30.06.1999) US

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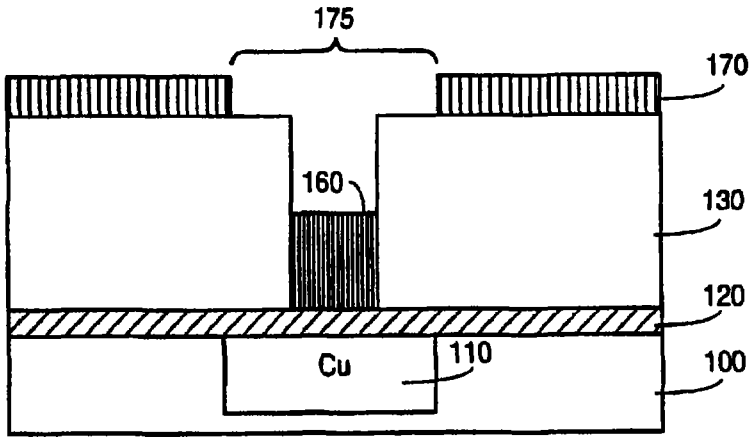
(81) Designated States *(national)*: AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BY, CA, CH, CN, CR, CU, CZ, DE, DK, DM, DZ, EE, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD, MG, MK, MN, MW, MX, MZ, NO, NZ, PL, PT, RO, RU, SD, SE, SG, SI, SK, SL, TJ, TM, TR, TT, TZ, UA, UG, US, UZ, VN, YU, ZA, ZW.

(84) Designated States *(regional)*: ARIPO patent (GH, GM, KE, LS, MW, MZ, SD, SL, SZ, TZ, UG, ZW), Eurasian patent (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European patent (AT, BE, CH, CY, DE, DK, ES, FI, FR, GB, GR, IE, IT, LU, MC, NL, PT, SE), OAPI patent (BF, BJ, CF, CG, CI, CM, GA, GN, GW, ML, MR, NE, SN, TD, TG).

**Published:**
— *With international search report.*
— *Before the expiration of the time limit for amending the claims and to be republished in the event of receipt of amendments.*

*For two-letter codes and other abbreviations, refer to the "Guidance Notes on Codes and Abbreviations" appearing at the beginning of each regular issue of the PCT Gazette.*

(54) Title: METHOD OF PROTECTING AN UNDERLYING WIRING LAYER DURING DUAL DAMASCENE PROCESSING




*G00001*

(57) Abstract: A method of forming an interconnection including the steps of forming a sacrificial material (160) that comprises a physical property that is generally insensitive to a photoreaction in a via (150) through a dielectric material (130) to a masking material (120) over a conductive material (110). The method also includes forming a trench (180) over in the dielectric material over the via (150) and removing the sacrificial material (160) from the via.

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